

Filename: #N/A

Variant: None

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LM27403 Buck

| Designator | Description | Manufacturer | PartNumber | Quantity |
|--|--|------------------------|--------------------|----------|
| !PCB1 | Printed Circuit Board | Any | PMP7935 | 1 |
| C1, C2, C3, C4, C5, C6, C7, C8 | CAP, CERM, 10uF, 25V, +/-10%, X5R, 1206 | MuRata | GRM31CR61E106KA12L | 8 |
| C9, C41 | CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0402 | MuRata | GRM1555C1H101JA01D | 2 |
| C10, C23, C40 | CAP, CERM, 0.1uF, 16V, +/-10%, X7R, 0402 | MuRata | GRM155R71C104KA88D | 3 |
| C11, C12, C13, C14, C15, C16, C17, C18, C19, C20, C21, C26, C27, C28, C29, C30, C31, C32, C33, C34, C35, C36 | CAP, CERM, 100uF, 6.3V, +/-20%, X5R, 1206 | MuRata | GRM31CR60J107ME39L | 22 |
| C22 | CAP, CERM, 0.047uF, 16V, +/-10%, X7R, 0402 | MuRata | GRM155R71C473KA01D | 1 |
| C24 | CAP, CERM, 680pF, 50V, +/-5%, C0G/NP0, 0603 | TDK | C1608C0G1H681J | 1 |
| C25 | CAP, CERM, 390pF, 50V, +/-5%, C0G/NP0, 0402 | MuRata | GRM1555C1H391JA01D | 1 |
| C37, C38 | CAP, CERM, 6800pF, 25V, +/-10%, X7R, 0402 | MuRata | GRM155R71E682KA01D | 2 |
| C39 | CAP, CERM, 4.7uF, 6.3V, +/-20%, X5R, 0402 | MuRata | GRM155R60J475ME87D | 1 |
| C42 | CAP, CERM, 2.2uF, 16V, +/-10%, X5R, 0603 | MuRata | GRM188R61C225KE15D | 1 |
| D1 | Diode, Schottky, 40V, 0.25A, SOD-523 | Diodes Inc. | SDM20U40-7-F | 1 |
| FID1, FID2, FID3, FID4, FID5, FID6 | Fiducial mark. There is nothing to buy or mount. | N/A | N/A | 6 |
| H1, H2, H5, H6 | Standoff, Hex, 0.5"L #4-40 Nylon | Keystone | 1902C | 4 |
| H3, H4, H7, H8 | Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead | B&F Fastener Supply | NY PMS 440 0025 PH | 4 |
| J1 | Conn Term Block, 2POS, 5.08mm PCB | Phoenix Contact | 1715721 | 1 |
| J2, J3 | Connector, RF Jack, Vertical, Gold, SMD | Amphenol | A-1JB | 2 |
| L1 | Inductor, MnZn Ferrite, WE-HCM, 0.25uH, 40A, 0.00032 ohm, SMD | Würth Elektronik eiSos | 744301025 | 1 |
| LBL1 | Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll | Brady | THT-14-423-10 | 1 |
| Q1, Q2 | NexFET Power Block, 30V, 40A, SON 5mm x 6mm | Texas Instruments | CSD87350Q5D | 2 |
| Q3 | Transistor, NPN, 40V, 0.2A, SOT-523 | Diodes Inc. | MMBT3904 | 1 |
| R1, R2 | RES, 6.81k ohm, 1%, 0.063W, 0402 | Vishay-Dale | CRCW04026K81FKED | 2 |
| R3 | RES, 2.15k ohm, 1%, 0.063W, 0402 | Vishay-Dale | CRCW04022K15FKED | 1 |
| R4 | RES, 100 ohm, 1%, 0.063W, 0402 | Vishay-Dale | CRCW0402100RFKED | 1 |
| R5, R7 | RES, 3.01k ohm, 1%, 0.063W, 0402 | Vishay-Dale | CRCW04023K01FKED | 2 |
| R6 | RES, 6.04k ohm, 1%, 0.063W, 0402 | Vishay-Dale | CRCW04026K04FKED | 1 |
| R8 | RES, 2.2 ohm, 5%, 0.125W, 0805 | Vishay-Dale | CRCW08052R20JNEA | 1 |
| R9 | RES, 45.3k ohm, 1%, 0.063W, 0402 | Vishay-Dale | CRCW040245K3FKED | 1 |
| R10 | RES, 10.0 ohm, 1%, 0.063W, 0402 | Vishay-Dale | CRCW040210R0FKED | 1 |
| R11 | RES, 10.0k ohm, 1%, 0.063W, 0402 | Vishay-Dale | CRCW040210K0FKED | 1 |
| R12 | RES, 47.5k ohm, 1%, 0.063W, 0402 | Vishay-Dale | CRCW040247K5FKED | 1 |
| R13 | RES, 10k ohm, 5%, 0.063W, 0402 | Vishay-Dale | CRCW040210K0JNED | 1 |
| R14 | RES, 82.5k ohm, 1%, 0.063W, 0402 | Vishay-Dale | CRCW040282K5FKED | 1 |
| R15 | RES, 2.2 ohm, 5%, 0.063W, 0402 | Vishay-Dale | CRCW04022R20JNED | 1 |
| R16, R17 | RES, 49.9 ohm, 1%, 0.1W, 0603 | Vishay-Dale | CRCW060349R9FKEA | 2 |
| T1, T2 | Terminal 50A Lug | Panduit | CB35-36-CY | 2 |

| Designator | Description | Manufacturer | PartNumber | Quantity |
|----------------------------------|--|------------------------|-------------------|-----------------|
| TP1, TP3, TP5, TP9 | Terminal, Turret, TH, Triple | Keystone | 1598-2 | 4 |
| TP2, TP6 | Test Point, TH, Miniature, Red | Keystone | 5000 | 2 |
| TP4, TP8, TP10, TP12, TP14 | Test Point, TH, Miniature, Black | Keystone | 5001 | 5 |
| TP7, TP11, TP13 | Test Point, TH, Miniature, White | Keystone | 5002 | 3 |
| U1 | Synchronous Buck Controller, 24-pin LLP, Pb-Free | National Semiconductor | LM27403SQX/NOPB | 1 |

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